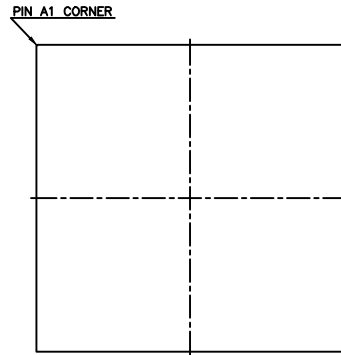
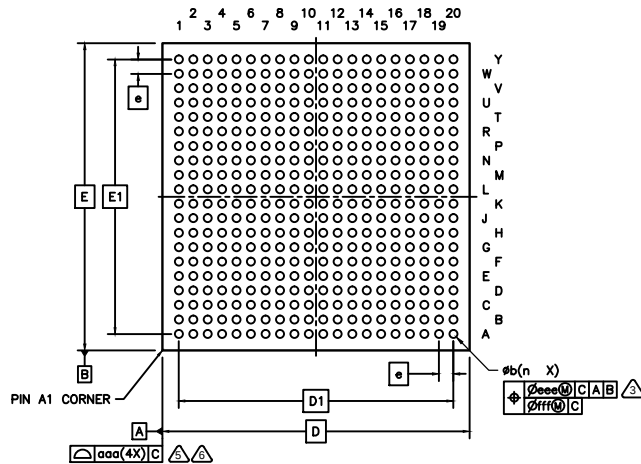
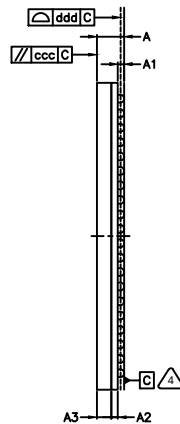




TOP VIEW



SIDE VIEW



BOTTOM VIEW

|                             | Symbol       | Common Dimensions |        |        |
|-----------------------------|--------------|-------------------|--------|--------|
|                             |              | MIN.              | NOM.   | MAX.   |
| Body Size:                  | X E<br>Y D   |                   | 17.000 | 17.000 |
| Ball Pitch:                 | e            |                   | 0.800  |        |
| Total Thickness:            | A            | 1.320             | 1.510  | 1.700  |
| Mold Cap Thickness:         | A3           |                   | 0.800  | Ref.   |
| Substrate Thickness:        | A2           |                   | 0.360  | Ref.   |
| Ball Diameter:              |              |                   | 0.450  |        |
| Stand Off:                  | A1           | 0.300             | 0.350  | 0.400  |
| Ball Width:                 | b            | 0.400             | 0.450  | 0.450  |
| Package Edge Tolerance:     | aaa          |                   | 0.150  |        |
| Mold Parallelism:           | ccc          |                   | 0.200  |        |
| Coplanarity:                | ddd          |                   | 0.200  |        |
| Ball Offset (Package):      | eee          |                   | 0.150  |        |
| Ball Offset (Ball):         | fff          |                   | 0.080  |        |
| Ball Count:                 | n            |                   | 400    |        |
| Edge Ball Center to Center: | X E1<br>Y D1 |                   | 15.200 | 15.200 |

NOTES: UNLESS OTHERWISE SPECIFIED

- DIMENSIONS AND TOLERANCES PER ANSI Y14.5M.
- ALL DIMENSIONS ARE IN MILLIMETERS.
- DIMENSION "b" IS MEASURED AT THE MAXIMUM SOLDER BALL DIAMETER, PARALLEL TO PRIMARY DATUM [C].
- PRIMARY DATUM [C] AND SEATING PLANE ARE DEFINED BY THE SPHERICAL CROWNS OF THE SOLDER BALLS.
- BILATERAL TOLERANCE ZONE IS APPLIED TO EACH SIDE OF THE PACKAGE BODY.
- EXACT SHAPE AND SIZE OF THIS FEATURE IS OPTIONAL.
- JEDEC REFERENCE: JEP95 DR4.5 AND MO-210

|                                                                   |                    |                         |           |
|-------------------------------------------------------------------|--------------------|-------------------------|-----------|
| Title: Package Outline Drawing                                    | Pkg Type: CABGA    | Document No: POD-250080 |           |
| Product Family: LFMXO4/LFMXO4D                                    | Pin Count: 400     |                         |           |
| Product Name: LFMXO4-050/080/110-BBG400<br>LFMXO4D-080/110-BBG400 | Pkg Size: 17x17 mm | Rev: B                  | PAGE: 3/3 |

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